Docket No.: 122.1457

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Nawalage Florence COORAY

Serial No. Group Art Unit:

Confirmation No.

Filed: June 28, 2001 Examiner:

For: THERMOSETTING FLUORINATED DIELECTRICS AND MULTILAYER CIRCUIT BOARDS

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Before calculation of the filing fee for the subject application, please amend the above-identified application as follows:

IN THE CLAIMS:

Please AMEND the pending claims and ADD new claims * in accordance with the following:

3. (AS ONCE AMENDED HEREIN) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1.

4. (AS ONCE AMENDED HEREIN) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1.

6. (AS NEW HEREIN) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

7. (AS NEW HEREIN) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

8. (AS NEW HEREIN) A multilayer circuit board comprising a dielectric film according to claim 6.

REMARKS

This Preliminary Amendment is submitted to delete multiple dependent claims as presented in the concurrently filed subject application. No new matter is presented.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

Date: June 28, 2001

By: ______________________
H. J. Staas
Registration No. 22,010

700 Eleventh Street, NW, Suite 500
Washington, D.C. 20001
(202) 434-1500

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please AMEND the following claims:

3. (ONCE AMENDED) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1 [or 2].

4. (ONCE AMENDED) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1 [or 2].

Please ADD the following claims:

6. (NEW) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

7. (NEW) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

8. (NEW) A multilayer circuit board comprising a dielectric film according to claim 6.